

AMENDMENT UNDER 37 C.F.R. § 1.111  
Appln. No. 09/786,787

PATENT APPLICATION

### VERSION WITH MARKINGS TO SHOW CHANGES MADE

Amend the paragraph found at line 18 of page 6 to line 14 of page 7 as follows (underlining indicates added text):

The invention satisfies the above objects by providing a non-circular via and a method for cutting away material about a centerline for a non-circular via for PCBs. The method of drilling the non-circular via will be by cutting or removing material away about a centerline with a process such as laser ablation or plasma ablation. This type of cutting away of material about a centerline is sometimes referred to as ablation of material as noted above and allows lateral movements to effect noncircular patterns. This invention utilizes this noncircular approach in three forms, convoluted circle or a square, an extended elongated via up to three times the diameter in depth and a trenched via. The convoluted circle or non-circular via is a Profile Power Micro-via. The Profile via has any shape other than round or circular to create an increased length in circumference over a round or circular format. The Profile via can have a non-circular wave form shape centered on the circumference or pitch circle diameter or an irregular shape that is not based on the round or circular form. A Three

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Diameter via or a 1-3D via is a through hole having two component dimensions where one is the major dimension of 1-3 length and other minor dimension is its breadth having 1D diameter. Finally, a micro milled trench forming a co-axialised structure is used for noise protection EMI protection and is typically elongated longer than 3 times the diameter of the standard circular Micro-via. The trench may have a length greater than two times the breadth of the trench.

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